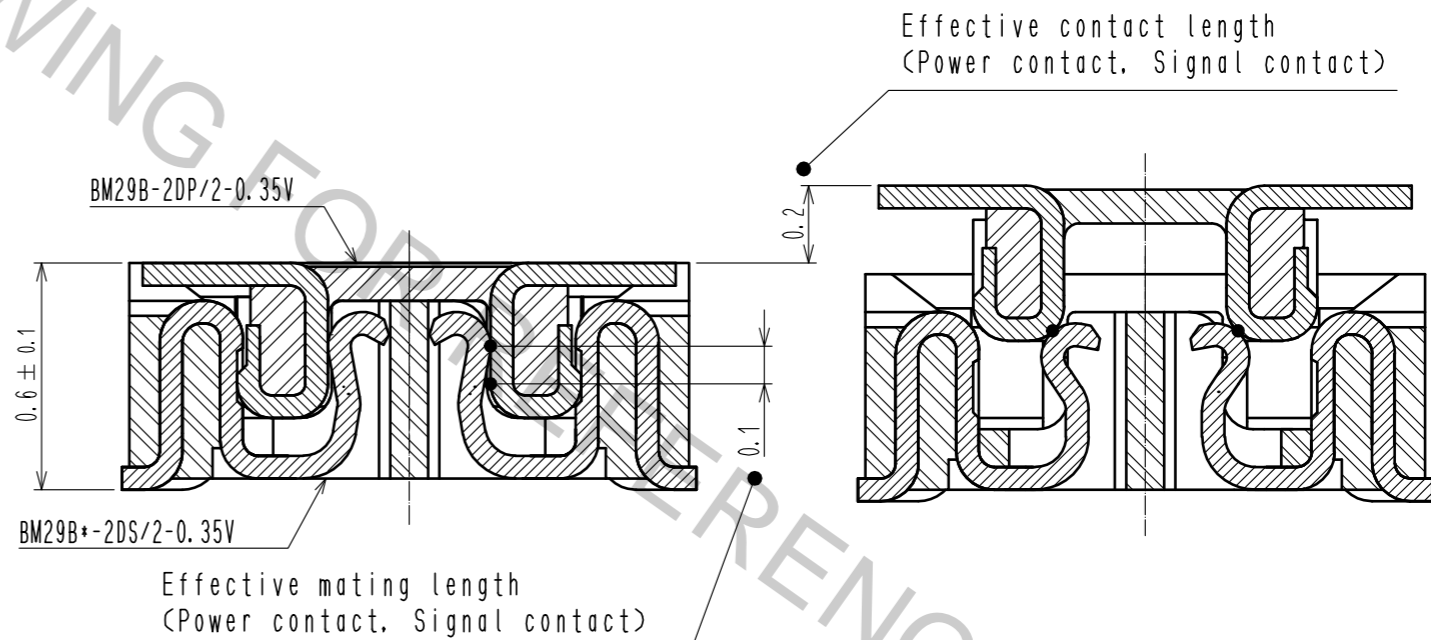
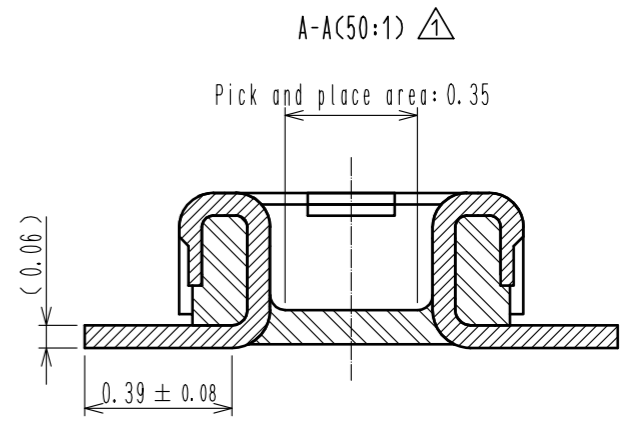
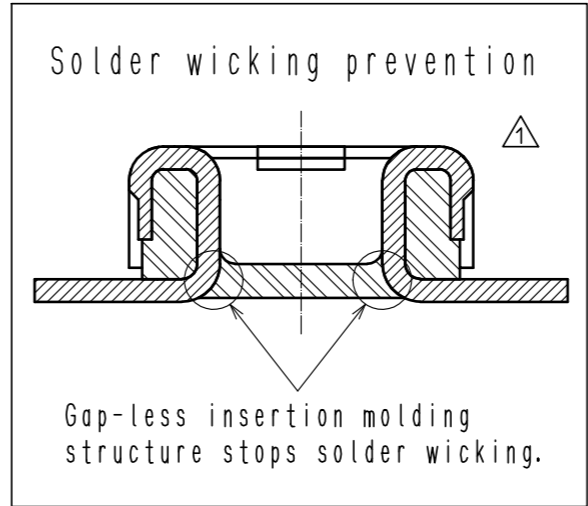
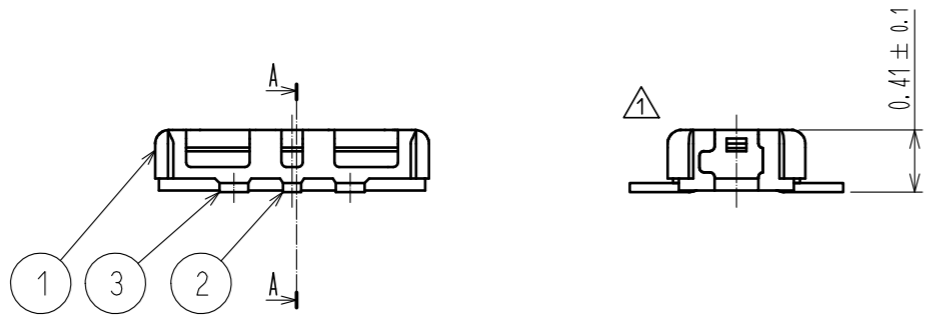
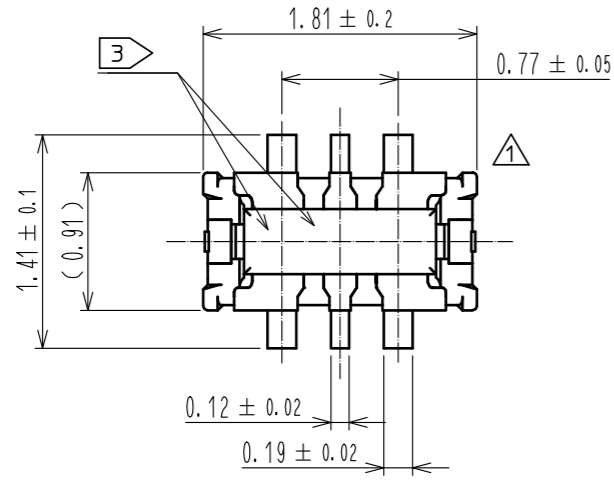


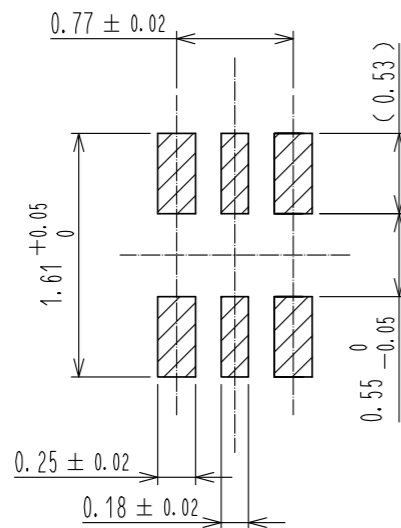
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- NOTE 1 . All lead co-planarity shall be 0.08mm MAX.  
 2 . Contact plating specifications  
 Contact area : Gold 0.05 μm MIN  
 SMT lead : Gold 0.05 μm MIN  
 Under plating : Nickel 1 μm MIN  
 ( Surface : Sealing )  
 3 . HRS mark and CAV No. are indicated in approx. position shown.

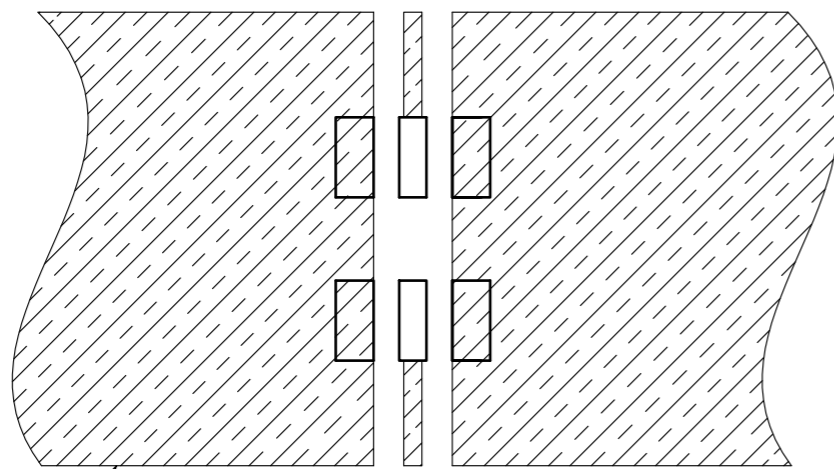
|                                      |                 |                          |            |  |                                   |                        |                  |
|--------------------------------------|-----------------|--------------------------|------------|--|-----------------------------------|------------------------|------------------|
| 3                                    | PHOSPHOR BRONZE | 2                        | 7          | PS   | CLEAR. REINFORCEMENT COLLAR       |                        |                  |
| 2                                    | PHOSPHOR BRONZE | 2                        | 6          | PS   | BLACK. PLASTIC REEL               |                        |                  |
| 1                                    | LCP             | UL94 V-0. BLACK          | 5          | POLYESTER                                  | CLEAR. COVER TAPE                 |                        |                  |
|                                      |                 |                          | 4          | PS   | SMOKE GRAY. EMBOSSED CARRIER TAPE |                        |                  |
| NO.                                  | MATERIAL        | FINISH . REMARKS         | NO.        | MATERIAL                                   | FINISH . REMARKS                  |                        |                  |
| UNITS<br>mm                          |                 | SCALE<br>20:1            | COUNT<br>6 | DESCRIPTION OF REVISIONS<br>DIS-H-00000474 | DESIGNED<br>TY. YAMASAKI          | CHECKED<br>WR. FUKUCHI | DATE<br>15.06.02 |
| <b>HRS</b> HIROSE ELECTRIC CO., LTD. |                 | APPROVED : MO. ISHIDA    | 15.03.23   | DRAWING NO.<br>EDC-362710-51-00            |                                   |                        |                  |
|                                      |                 | CHECKED : KY. MIDORIKAWA | 15.03.23   | PART NO.<br>BM29B-2DP/2-0.35V(51)          |                                   |                        |                  |
|                                      |                 | DESIGNED : TY. YAMASAKI  | 15.03.23   | CODE NO.<br>CL673-7002-0-51                |                                   |                        |                  |
|                                      |                 | DRAWN : TY. YAMASAKI     | 15.03.23   |  |                                   |                        |                  |

◆ Recommended PCB layout

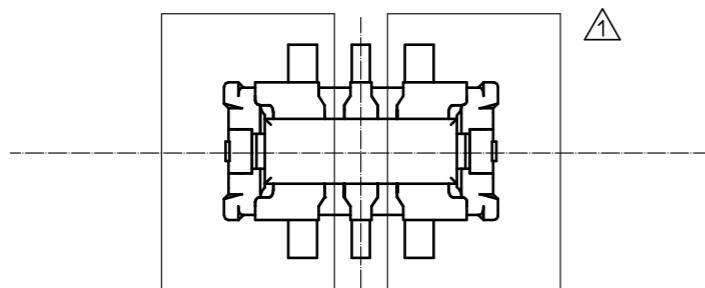


◆ Recommended metal mask dimensions  
 Metal mask thickness : 100 μm  
 (Open ratio : 100% for PCB layout)

◆ Recommended electrical circuit layout

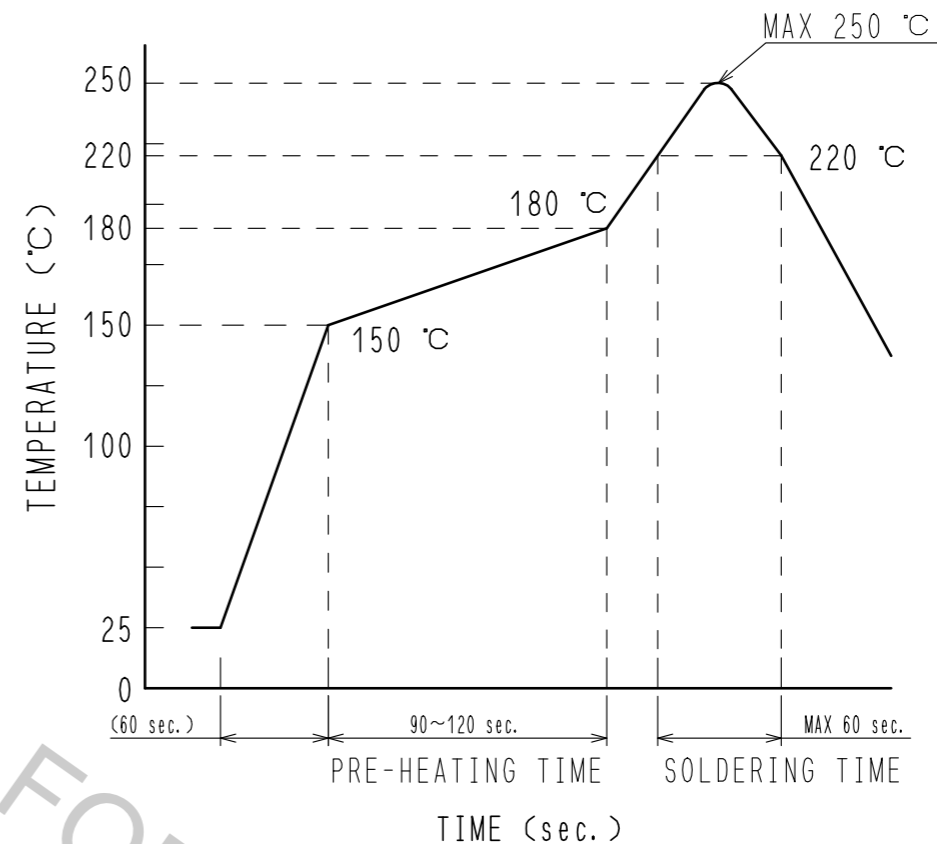


Electrical circuit



Power pin unit

4 Recommended reflow temperature profile using lead-free solder paste.

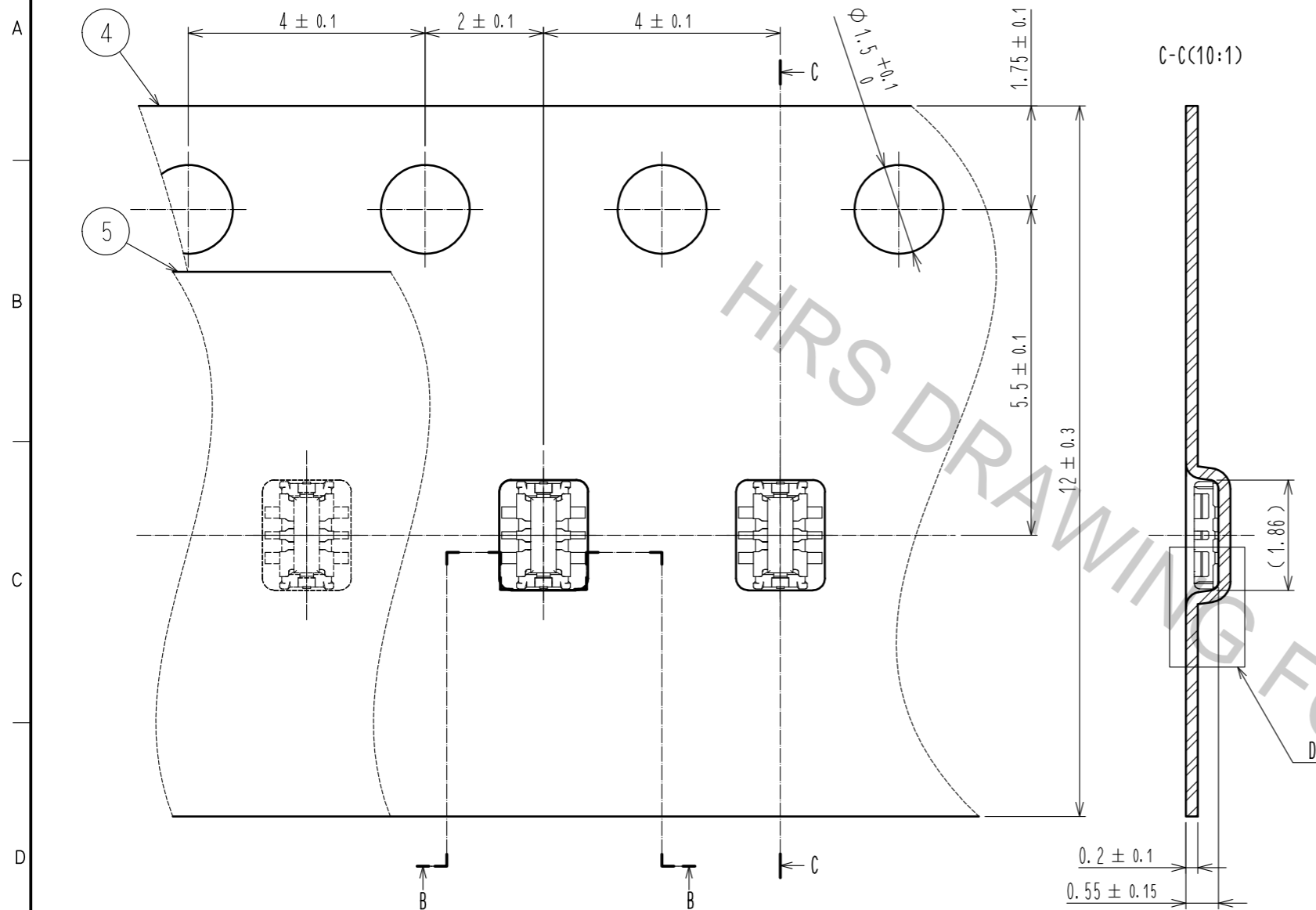


Reflow method: IR reflow  
 Number of reflow cycles: 2 cycles MAX.  
 1) Reflow time  
 Duration above 220°C: 60 sec MAX.  
 (Peak temperature: 250°C MAX)  
 2) Pre-heat time  
 Pre-heat temperature (MIN): 150°C  
 Pre-heat temperature (MAX): 180°C  
 Pre-heat time: 90-120 sec.

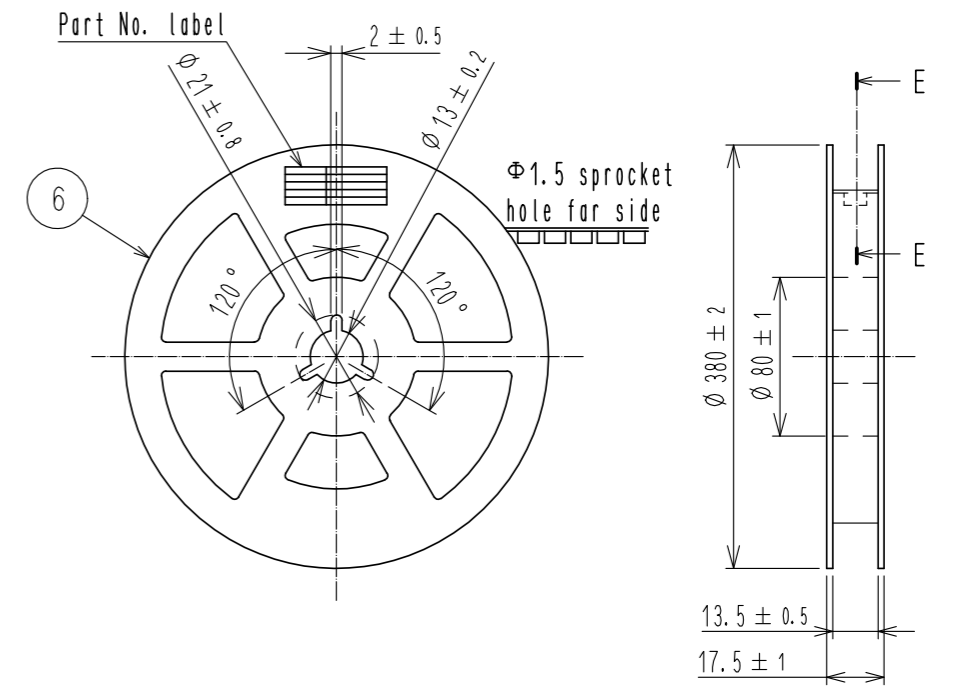
- 4 The temperatures mentioned above refer to the PCB surface temperature near the connector leads. The temperature profiles are based on the above conditions. In individual applications the actual temperature may vary, depending on solder paste type, volume/thickness and board size/thickness. Consult your solder paste and equipment manufacturer for specific recommendations.
- 5 Please contact us in case you will make different settings from our recommendation.

|            |             |                       |
|------------|-------------|-----------------------|
| <b>HRS</b> | DRAWING NO. | EDC-362710-51-00      |
|            | PART NO.    | BM29B-2DP/2-0.35V(51) |
|            | CODE NO.    | CL673-7002-0-51       |
|            |             | △ 2/3                 |

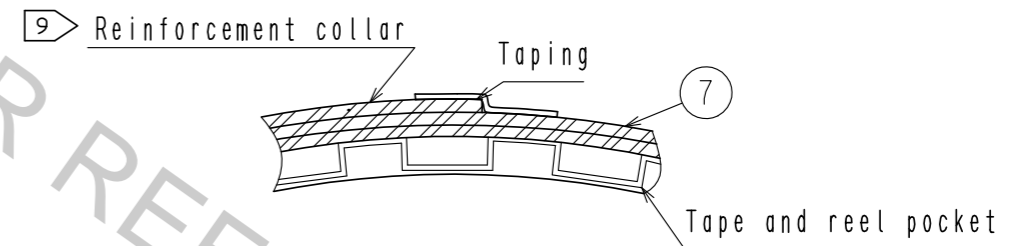
Embossed carrier tape packaging (10:1)



Style and dimension of reel (Free)



E-E (Free)

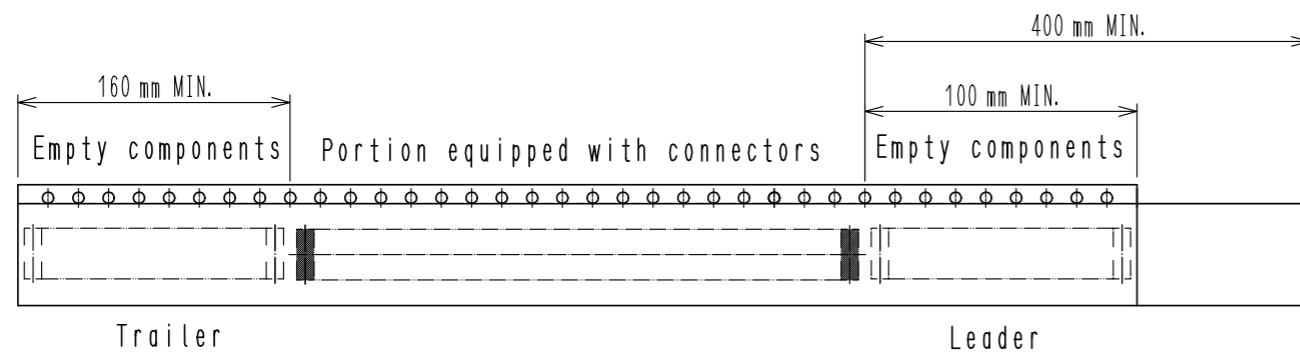
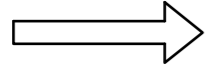


Detail of part No. label

|       |                   |
|-------|-------------------|
| 製造年月日 | ** ** *           |
| 製品コード | CL0673-7002-0-51  |
| 製品名   | BM29B-2DP/2-0.35V |
| 数量    | 20,000            |
| 納入者   | ヒロセ電機(株)          |

Data of manufactured  
Code No.  
Part No.  
Quantity  
Supplier

Direction of unreeling



Taping (Free)

- 6 . Per reel 20,000 connectors.
- 7 . The dimensions in parentheses are for reference.
- 8 . Refer to JIS C 0806 and IEC60286-3  
(Packaging of components for automatic handling)
- 9 . Wrap a reinforcing collar made by polystyrene to the surface of emboss reel at the termination side in order to protect emboss carrier tape, top cover tape.

|            |             |                       |
|------------|-------------|-----------------------|
| <b>HRS</b> | DRAWING NO. | EDC-362710-51-00      |
|            | PART NO.    | BM29B-2DP/2-0.35V(51) |
|            | CODE NO.    | CL673-7002-0-51       |
|            |             | 3/3                   |